

優貝克科技股份有限公司 ULVAC

Display manufacturing equipment

Organic EL manufacturing system



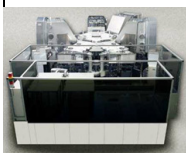
SOLCIET, SATELLA, NEW-ZELDA

A complete lineup including a research system for materials development, a cluster system for low-volume production, and an in-line system for mass-production. The lineup supports a complete range of organic EL applications, with systems for micromolecular materials and systems for macromolecular organic materials

Application: Organic EL displays

Single-substrate sputtering systems

SMD Series

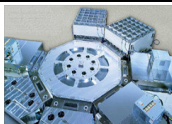


The SMD Series are single-substrate sputtering systems for deposition of films such as metal films and ITO films. ULVAC has delivered a large number of these systems, for use in a wide range of production environments. ULVAC responds rapidly to feedback from production sites to improve the reliability of these models.

Application: Thin-film transistors (TFTs), Color filters

Single-substrate plasma CVD systems

CMD Series



The CMD Series are single-substrate CVD systems for deposition of silicon oxide and nitride films using SiH₄ or TEOS. A high-frequency (27.12 MHz) power supply enables high-quality film deposition

Application: Low-temperature P-Si, α -Si TFTs

Devices for the Semiconductor Industry

ENTRON™-PVD/CVD Metallization System for 300 mm wafers



ENTRON-PVD/CVD takes up less space than conventional metallization systems, and was developed as a low cost system for manufacturing more highly miniaturized and higher-performance devices. With a design incorporating next-generation fab concepts, Entron supports front-end and back-end process application, such as Silicide process of Co, Ni, etc. and supports conventional aluminum wiring technology, and has process modules (SIS, ALD) for the advanced copper wiring technology set to become the mainstream in the years ahead.

Devices for the Semiconductor Industry

Ashing System Luminous NA Series



Application:

High dose ion implant stripping process (1×10^{16} atoms/cm² or higher) and polymer removal in front end process

Wafer process that requires CF-4 addition process (electronic parts and LEDs)

Chip size package and bump process

CCD color filter manufacturing process

Devices for the Semiconductor Industry

Dry Etching System for Production

NE-5700/NE-7800



Application:

Compound semiconductor (LED, LD and RF devices), Power devices (IGBT, SiC)

Metal, Dielectric, Polymer, Gate electrode etching

Ferro electric material, Noble metal etching

Ferro magnetic material etching

Devices for the Semiconductor Industry

Load-lock type Plasma-CVD System

CC-200/400



Application:

Compound-related devices of LED, LD and highspeed devices,

Organic EL system for R&D use

Solar battery system for R&D use

MEMS

Power devices

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